



# LOCTITE® 3730™

January 2009

## PRODUCT DESCRIPTION

LOCTITE® 3730™ provides the following product characteristics:

<b>Technology</b>	Acrylic
<b>Chemical Type</b>	Acrylate
<b>Appearance (uncured)</b>	Transparent amber liquid <sup>LMS</sup>
<b>Components</b>	One component - requires no mixing
<b>Viscosity</b>	Medium
<b>Cure</b>	Ultraviolet (UV)/ visible light
<b>Cure Benefit</b>	Production - high speed curing
<b>Application</b>	Sealing or LCD end-sealing

LOCTITE® 3730™ is a UV light curable sealant for LCD end-sealing applications.

## TYPICAL PROPERTIES OF UNCURED MATERIAL

Flash Point - See MSDS

Viscosity @ 25°C, mPa·s (cP):

Haake viscometer, PK1, 2°:

Constant shear rate @ 20 s<sup>-1</sup> 22,000 to 28,000<sup>LMS</sup>

## TYPICAL CURING PERFORMANCE

LOCTITE® 3730™ cures when exposed to UV radiation of 365 nm. To obtain a full cure on surfaces exposed to air, radiation at 220 to 260nm is required. The cure rate and ultimate depth of cure will depend on the UV intensity, the spectral distribution of the light source, the exposure time and the light transmittance of the substrates.

## Tack Free Time

Tack Free Time is the time required to achieve a tack free surface

Tack Free Time, seconds:

High pressure mercury arc light source:

40 mW/cm<sup>2</sup>, measured @ 365 nm, ≤15<sup>LMS</sup>

## TYPICAL PROPERTIES OF CURED MATERIAL

### Physical Properties:

Coefficient of Thermal Expansion,  
ISO 11359-2, K<sup>-1</sup>:

-30 °C	55×10 <sup>-6</sup>
30 °C	140×10 <sup>-6</sup>
50 °C to 150 °C	190×10 <sup>-6</sup>

Shore Hardness, ISO 868, Durometer D 82

UV Depth of Cure, mm:

40 mW/cm<sup>2</sup>, measured @ 365 nm, for 50 seconds, using a high pressure mercury arc light source ≥2.5<sup>LMS</sup>

### Electrical Properties:

Surface Resistivity, IEC 60093, Ω	4.0×10 <sup>15</sup>
Volume Resistivity, IEC 60093, Ω·cm	7.0×10 <sup>12</sup>
Dielectric Breakdown Strength, IEC 60243-1, kV/mm	17

Dielectric Constant / Dissipation Factor, IEC 60250:

10 kHz	4.4 / 0.05
1 MHz	3.8 / 0.06
10 MHz	3.8 / <0.01

## TYPICAL PERFORMANCE OF CURED MATERIAL

### Adhesive Properties

Cured @ 6 mW/cm<sup>2</sup>, measured @ 365 nm, for 5 minutes using a Philips HPR125 light source

Tensile Strength, ISO 6922:

Steel pin (grit blasted) to Glass	N/mm <sup>2</sup>	≥3 <sup>LMS</sup>
	(psi)	(≥435)

Torsional Shear Strength, ASTM D 3658:

Aluminum hex button (grit blasted) to Glass	N·m	140
	(lb·ft)	(103)

Cured @ 100 mW/cm<sup>2</sup>, measured @ 365 nm, for 40 seconds using a high pressure mercury arc light source

Tensile Strength, ISO 6922:

Steel pin (grit blasted) to Glass	N/mm <sup>2</sup>	11
	(psi)	(1,595)

## TYPICAL ENVIRONMENTAL RESISTANCE

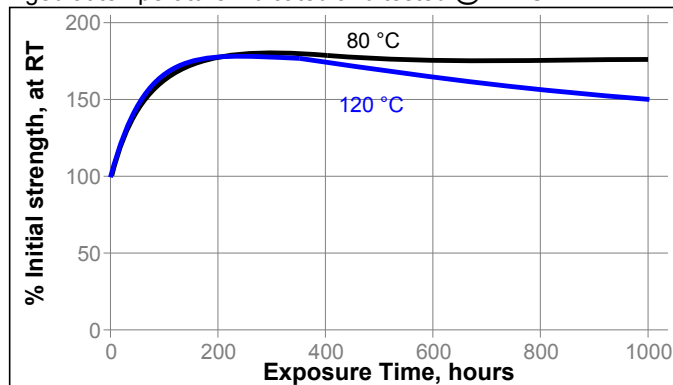
Cured @ 100 mW/cm<sup>2</sup>, measured @ 365 nm, for 40 seconds plus 1 week @ 22 °C

Tensile Strength, ISO 6922:

Steel pin (grit blasted) to Glass

## Heat Aging

Aged at temperature indicated and tested @ 22 °C



## Chemical/Solvent Resistance

Aged under conditions indicated and tested @ 22 °C.

Environment	°C	% of initial strength		
		100 h	500 h	1000 h
Heat/humidity 90% RH	40	130	120	110

**GENERAL INFORMATION**

**This product is not recommended for use in pure oxygen and/or oxygen rich systems and should not be selected as a sealant for chlorine or other strong oxidizing materials**

**For safe handling information on this product, consult the Material Safety Data Sheet (MSDS).**

**Directions for use:**

1. This product is light sensitive; exposure to daylight, UV light and artificial lighting should be kept to a minimum during storage and handling.
2. The product should be dispensed from applicators with black feedlines.
3. For best performance bond surfaces should be clean and free from grease.
4. Cure rate is dependent on lamp intensity, distance from light source, depth of cure needed or bondline gap and light transmittance of the substrate through which the radiation must pass.
5. Cooling should be provided for temperature sensitive substrates such as thermoplastics.
6. Plastic grades should be checked for risk of stress cracking when exposed to liquid adhesive.
7. Excess uncured adhesive can be wiped away with organic solvent (e.g. Acetone).
8. Bonds should be allowed to cool before subjecting to any service loads.

**Loctite Material Specification<sup>LMS</sup>**

LMS dated January 11, 2001. Test reports for each batch are available for the indicated properties. LMS test reports include selected QC test parameters considered appropriate to specifications for customer use. Additionally, comprehensive controls are in place to assure product quality and consistency. Special customer specification requirements may be coordinated through Henkel Quality.

**Storage**

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

**Optimal Storage: 8 °C to 21 °C. Storage below 8 °C or greater than 28 °C can adversely affect product properties.**

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

**Conversions**

$(^{\circ}\text{C} \times 1.8) + 32 = ^{\circ}\text{F}$   
 $\text{kV/mm} \times 25.4 = \text{V/mil}$   
 $\text{mm} / 25.4 = \text{inches}$   
 $\mu\text{m} / 25.4 = \text{mil}$   
 $\text{N} \times 0.225 = \text{lb}$   
 $\text{N/mm} \times 5.71 = \text{lb/in}$   
 $\text{N/mm}^2 \times 145 = \text{psi}$   
 $\text{MPa} \times 145 = \text{psi}$   
 $\text{N}\cdot\text{m} \times 8.851 = \text{lb}\cdot\text{in}$   
 $\text{N}\cdot\text{m} \times 0.738 = \text{lb}\cdot\text{ft}$   
 $\text{N}\cdot\text{mm} \times 0.142 = \text{oz}\cdot\text{in}$   
 $\text{mPa}\cdot\text{s} = \text{cP}$

**Note**

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

**Trademark usage**

Except as otherwise noted, all trademarks in this document are trademarks of Henkel Corporation in the U.S. and elsewhere. ® denotes a trademark registered in the U.S. Patent and Trademark Office.

Reference 1.1

# Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Loctite:](#)

[2892021](#)